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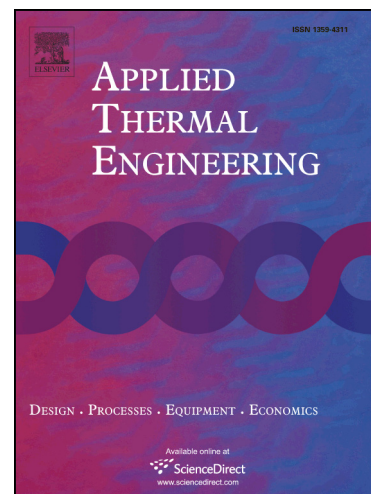
Numerical investigation of a thermal baffle design for single ground heat exchanger

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PII: S1359-4311(16)30594-4
DOI: <http://dx.doi.org/10.1016/j.applthermaleng.2016.04.106>
Reference: ATE 8154

To appear in: *Applied Thermal Engineering*

Received Date: 15 February 2016
Accepted Date: 21 April 2016



Please cite this article as: S. Chen, J. Mao, P. Hou, C. Li, Numerical investigation of a thermal baffle design for single ground heat exchanger, *Applied Thermal Engineering* (2016), doi: <http://dx.doi.org/10.1016/j.applthermaleng.2016.04.106>

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Full title: Numerical investigation of a thermal baffle design for single ground heat exchanger

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